## **Amendments to the Claims**

This listing of claims will replace all prior versions of claims in the application.

1-9. (cancel)

Please insert new claims 10-20 as follows:

10. (New) A heat-curable adhesive composition comprising:

an ethylene-glycidyl (meth)acrylate copolymer;

a low density polyethylene;

an ethylene- $\alpha$ -olefin copolymer; and

a heat curing agent for said ethylene-glycidyl (meth)acrylate copolymer.

- 11. (New) The heat-curable adhesive composition of claim 10, wherein the minimum density of said low density polyethylene is at least about 0.910 as measured according to ASTM D1248-84.
- 12. (New) The heat-curable adhesive composition of claim 10, wherein the maximum density of said low density polyethylene is up to about 0.925 as measured according to ASTM D1248-84.
- 13. (New) The heat-curable adhesive composition of claim 10, wherein, in said ethylene- $\alpha$ -olefin copolymer, the polymerization ratio of ethylene to  $\alpha$ -olefin is from about 90:10 to about 10:90.
- 14. (New) The heat curable adhesive composition of claim 10, wherein the minimum density of said ethylene-α-olefin copolymer is about 0.850 as measured according to ASTM D1248-84.
- 15. (New) The heat curable adhesive composition of claim 10, wherein the maximum density of said ethylene- $\alpha$ -olefin copolymer is up to about 0.909 as measured according to ASTM D1248-84.

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16. (New) The heat-curable adhesive composition of claim 10, wherein said heat curing agent comprises a rosin having a carboxyl group in the molecule.

- 17. (New) The heat-curable adhesive composition of claim 10, wherein said composition is in the form of a thin film.
- 18. (New) The heat-curable adhesive composition of claim 17, wherein said film has a thickness from about 5 to about 80  $\mu m$ .
- 19. (New) The heat-curable adhesive composition of claim 10, wherein, after post-curing, the composition has a dielectric constant of about 2.5 or less, and a dielectric loss tangent of about 0.015 or less when measured at the frequency of about 1 GHz.
- 20. (New) The heat-curable adhesive composition of claim 10 having an adhesive.